

# Yuefeng Li

## List of Publications by Year in descending order

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8  
papers

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1936888

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2053342

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times ranked

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#	ARTICLE	IF	CITATIONS
1	Effect of Soldering Temperature on the Reliability of Sn-Ag-Cu Lead-Free Solder Joints. Journal of Electronic Materials, 2021, 50, 869-880.	1.0	7
2	Effect of the Welding Process on the Microstructure and Mechanical Properties of Au/Sn <sup>3.0</sup> Ag <sup>0.5</sup> Cu/Cu Solder Joints. Journal of Electronic Materials, 2022, 51, 1597-1607.	1.0	6
3	The Effect of Different Filament Arrangements on Thermal and Optical Performances of LED Bulbs. Applied Sciences (Switzerland), 2020, 10, 1373.	1.3	5
4	Research on the Mechanical and Performance Effects of Flux on Solder Layer Interface Voids. Journal of Electronic Materials, 2021, 50, 6629-6638.	1.0	4
5	Thermal conductivity anisotropy of expanded graphite/ chlorate salt composites for thermal energy storage. Soft Materials, 2021, 19, 78-88.	0.8	2
6	Effect of Different Soldering Temperatures on the Solder Joints of Flip-Chip LED Chips. Journal of Electronic Materials, 2021, 50, 796-807.	1.0	2
7	Research on Microstructure and Shear Behavior of Au/Sn-Ag-Cu/Cu Lead-free Solder Joints at Different Soldering Temperatures. Journal of Electronic Materials, 2021, 50, 5965-5980.	1.0	1
8	Effect of grain size on the interface structure and shear behavior of lead-free solder joints. Journal of Materials Science: Materials in Electronics, 2021, 32, 21620-21630.	1.1	0